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Patent

Attorney Docket No.: MTI-31607

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of : Teck Kheng Lee
Serial No. : 10/050,507
Confirmation No. : 7687
Filing Date : January 16, 2002
For : Elimination of RDL Using Tape Base Flip Chip on Flex for Die Stacking
Group Art Unit : 2812

CERTIFICATION UNDER 37 CFR 1.8(a) and 1.10

I hereby certify that, on the date shown below, this correspondence is being:

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37 CFR 1.8(a)
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37 CFR 1.10
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- Date: March 7, 2002

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INFORMATION DISCLOSURE STATEMENT UNDER 37 C.F.R. §1.97/98

In compliance with Applicant's duty of disclosure as set forth in 37 C.F.R. §1.56, listed on the attached equivalent to Form PTO-1449 are those patents and other publications known to the Applicant which may be considered material to the patentability of the claims of the above-captioned application.

The Applicant respectfully requests that the documents listed on the attached equivalent to Form PTO-1449 be considered by the Examiner, that these references be made of record in the present applicant, and that an initialed copy of the attached equivalent to Form PTO-1449 be returned to the undersigned in accordance with MPEP 609.

Respectfully submitted,

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Dated: March 7, 2002

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U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE Washington, D.C. 20231 INFORMATION DISCLOSURE STATEMENT BY APPLICANT	ATTY. DOCKET NO.	Serial No.
	MTI-31607	10/050,507
	Applicant	Confirmation No.
	Lee, Teck Kheng	7687
	Filing Date	Group Art Unit
	01-16-02	2812

U.S. PATENT DOCUMENTS

		Patent Number	Issue Date	Patentee	U.S. Class	Sub-Class	Filing Date
	A1	5,710,071	01-20-98	Beddingfield et al.	438	108	12-04-95
	A2	6,048,755	04-11-00	Jiang et al.	438	118	11-12-98
	A3	6,177,723	01-23-01	Eng et al.	257	691	12-17-97
	A4	6,222,265	04-24-01	Akram et al.	257	723	12-17-99
	A5	6,232,666	05-15-01	Corisis et al.	257	774	12-04-98
	A6	6,242,932	06-05-01	Hembree	324	755	02-19-99
	A7	6,265,775	07-24-01	Seyyedy	257	737	09-08-99
	A8	6,291,265	09-18-01	Mess	438	107	02-09-00
	A9	6,295,730	10-02-01	Akram	29	843	09-02-99

FOREIGN PATENT OR PUBLISHED FOREIGN PATENT APPLICATION

Examiner Initial		Document Number	Publication Date	Country	Int'l Class	Sub-Class	Translation (Yes/No)
	BI						

OTHER DOCUMENTS (Including Author, Title, Date, Relevant Pages, Place of Publication)

Examiner Initial		Non-Patent Document
	C1	

Examiner Initials	Date Considered
EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.	